TECHNICAL DATA SHEET



WS482 WATER SOLUBLE CORED WIRE

FEATURES

- Halide-Free, ORM0
- High Activity Level
- Excellent Thermal Transfer and Wetting
- Compatible with all Leaded and Lead-Free Alloys
- Extended Cleaning Window
- Residues Easily Removed with DI Water

DESCRIPTION

WS482 is a unique water soluble, halide-free flux cored wire solder. WS482 provides excellent wetting and soldering characteristics with a thermally robust formula allowing it to be processed with all leaded and lead-free solder alloys. WS482 post-process residues are non-corrosive and will not tarnish PCBs or bare copper. WS482 flux residue must be completely removed with DI water within 5-7 days of processing. WS482 flux classification is ORM0 per J-STD-004B.

STANDARD AVAILABILITY

WS482 cored wire is available in common alloys, diameters and spool sizes. Non-common alloys, diameters and spool sizes may be available upon special request. Contact AIM for detailed availability information.

APPLICATION

Solder iron tip temperature should be between 350° - 400°C (650° - 750°F) for lead bearing alloys, 370° - 425°C (700° - 800°F) for common lead-free alloys.



HANDLING & STORAGE

Time	Parameters	
3 years	Cool < 30°C (< 86°F) Dry < 75% Rh	

Store cored wire in a clean, dry area away from moisture and sunlight. Do not freeze this product.

CLEANING

Post-process residues should be removed with deionized water at 38° - 60°C (100° - 140°F). An in-line or other pressurized spray cleaning system is recommended.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

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TEST DATA SUMMARY

Name	Test Method	Results		
IPC Flux Classification	J-STD-004	ORM0		
IPC Flux Classification	J-STD-004B 3.3.1	ORM0		
Name	Test Method	Typical Image Results		
Copper Mirror	J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32	LOW	CIN YUS 482 GONTRUL	
Corrosion	J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15	PASS	Before After	
Quantitative Halides	J-STD-004B 3.4.1.3 IPC-TM-650 2.3.28.1	0.0%		
Qualitative Halides, Silver Chromate	J-STD-004B 3.5.1.1 IPC-TM-650 2.3.33	PASS *Discoloration due to amine reaction		
Qualitative Halides, Fluoride Spot	J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1	No Fluoride		
Surface Insulation Resistance *After Cleaning	J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7	All measurements on test patterns exceed 100 MΩ	13	
Acid Value Determination	J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13	119 mgKOH/g flux Typical		
Visual	J-STD-004B 3.4.2.5	PASS		
Wetting	J-STD-005A 3.9 IPC-TM-650 2.4.45	PASS		
Spread	J-STD-004B 3.7.2 IPC-TM650 2.4.46	PASS		
Cleanliness	TM125-03	PASS		

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